



# HexPly<sup>®</sup> M78.1

110 – 160°C Curing Epoxy Matrix



## Product Data Sheet

### Description

HexPly<sup>®</sup> M78.1 is a formulated, hot melt epoxy resin matrix, especially designed for prepreg applications where short cure cycles using temperatures  $\geq 110^{\circ}\text{C}$  are required. Due to its high reactivity, HexPly<sup>®</sup> M78.1 can be used for economic, environmentally friendly and fast manufacture of industrial composites.

HexPly<sup>®</sup> M78.1 is based on a modified, toughened epoxy resin and a highly reactive curative package applicable for pre-impregnation into carbon, glass or aramide fibers, combining the outstanding feature of being curable within e.g, 7 minutes at  $120^{\circ}\text{C}$  and with a shelf-life of at least 2 weeks at ambient conditions.

The versatility of HexPly<sup>®</sup> M78.1 allows a range of processing temperatures, recommended from  $110^{\circ}\text{C}$  up to  $160^{\circ}\text{C}$ . Following a cure cycle in the recommended range, HexPly<sup>®</sup> M78.1 demonstrates superior mechanical properties and high glass transition temperatures. The controlled-flow characteristics of HexPly<sup>®</sup> M78.1 offers excellent adhesion to auxiliary and core materials like aluminum, wood, thermoplastics and elastomers.

The solvent-free, non-corrosive character of HexPly<sup>®</sup> M78.1 offsets the commonly known drawbacks of in-house prepreg systems that typically include hazardous components causing limitations regarding environmental, health and safety conditions.

### Benefits and Features

- Versatile, short cure cycles:  $110 - 160^{\circ}\text{C}$ , 18-1.5 minutes respectively
- Optimum cure cycle  $25 - 120^{\circ}\text{C}$  at  $20^{\circ}\text{C}/\text{minute}$ , 7 minutes at  $120^{\circ}\text{C}$
- Outstanding shelf life performance,  $\geq 2$  weeks at  $+23^{\circ}\text{C}$
- Excellent adhesion to core materials (wood, aluminum, thermoplastics, elastomers) by controlled flow technology
- Suitable for thin and thick laminates
- Well adapted to pressure moulding processes, suitable for a range of pressures (1 to 10 bar)
- Good flexibility, convenient handling and good adhesion to moulds by low tack
- Good surface finish
- Full REACH compliance
- Solvent-free, non-aggressive, no observable exposure limits

### Resin Matrix Properties

#### *Dynamic Thermal Properties*

by DSC (ISO 11357-5)

Cure	$-40$ to $270^{\circ}\text{C}$ @ $10^{\circ}\text{C}/\text{min}$
$T_{\text{Onset}}$	$110 - 125^{\circ}\text{C}$
$T_{\text{Peak}}$	$130 - 140^{\circ}\text{C}$
Enthalpy	250-400 J/g



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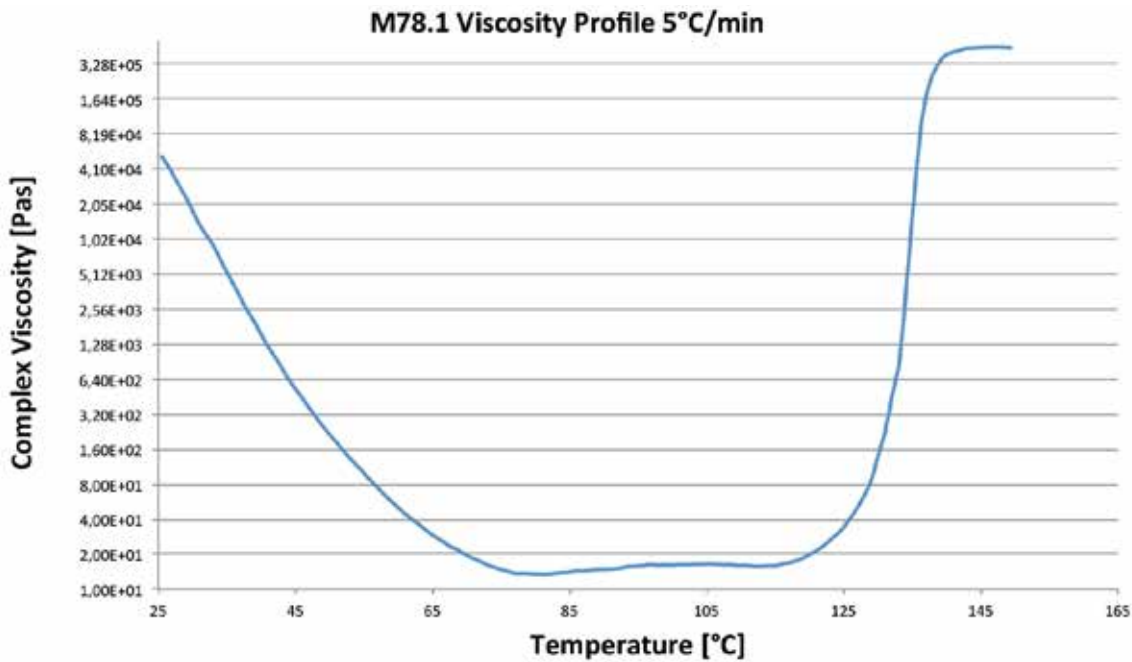
## Isothermal Cure Properties by DSC

Temperature	Cure Time (95%)*
110°C	18 minutes
120°C	7 minutes
130°C	5 minutes
140°C	3 minutes
150°C	2 minutes
160°C	1.5 minutes

\*time to 95% conversion (ISO 11357-5)

- Tg after 5 minutes at 130°C: 125°C (DSC, ISO 11357-2, 20°C/min)
- Density: 1.1-1.25 g/cm<sup>3</sup>
- Color: Milky

## Dynamic Viscosity



Minimum Viscosity: 13.5 Pas @80°C (controlled flow technology)



## Prepreg-Types and Mechanical Properties after Curing

Product	Reinforcement				Physical Properties				Mechanical Properties	
	Fiber	Fabric	Fiber Weight [g/m <sup>2</sup> ]	Orientation 0°/90°/+45°/+45° [g/m <sup>2</sup> ]	Cured Ply Thickness [mm]	Weight [g/m <sup>2</sup> ]	Resin Content [%]	Resin Flow [%]	Tensile Strength [MPa]	Tensile Modulus [GPa]
<b>M78.1/42%/LBB450/C</b>	Carbon	non-woven	450	157/0/147/147	0,53	776	42	20	0°:1020 45°:800	0°: 49 45°: 43
<b>M78.1/34%/LT570/G+F</b>	Glass	non-woven + fleece	560	432/75/0/0 + fleece 35	0,45	848	34	15	800	32
<b>M78.1/35%/LBB790/G+F</b>	Glass	non-woven + fleece	787	425/0/150/150 + fleece 50	0,67	1215	35	15	0°: 660 45°:240	0°: 27.7 45°:16.2
<b>M78.1/34%/L845/G+F</b>	Glass	non-woven + fleece	845	720/0/0/0 + fleece 100	0,70	1280	34	15	900	36
<b>M78.1/39%/UD120/CHS</b>	Carbon	UD	120	120/0/0/0	0,13	197	39	20	2400	128

Mechanical data are based on a cure cycle of 130°C, 15 min, 5 bar.

### Curing Conditions

- Recommended heat-up rate: 5 - 25°C/min
- Recommended cure cycle: 25-120°C at 20°C/min, 7 minutes at 120°C
- Pressure range: 1-10 bars

The optimum cure cycle, heat-up rate and dwell period is dependent on component size, layup construction, oven capacity and thermal mass of tool.

### Storage Stability

- Out-life
  - @ + 23°C ≥ 2 weeks
  - @ + 5°C TBD
  - @ - 18°C 18 months



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## Precautions for Use

The usual precautions when handling uncured synthetic resins and fine fibrous materials should be observed, and a Safety Data Sheet is available for this product. The use of clean disposable inert gloves provides protection for the operator and avoids contamination of material and components.

## For more information

Hexcel is a leading worldwide supplier of composite materials to aerospace and industrial markets. Our comprehensive range includes:

- HexTow<sup>®</sup> carbon fibers
- HexFlow<sup>®</sup> RTM resins
- Acousti-CAP<sup>®</sup> sound attenuating honeycomb
- HexForce<sup>®</sup> reinforcements
- Redux<sup>®</sup> adhesives
- Engineered core
- HexPly<sup>®</sup> prepregs
- HexTOOL<sup>®</sup> tooling materials
- Engineered products
- HexMC<sup>®</sup> molding compounds
- HexWeb<sup>®</sup> honeycombs

For US quotes, orders and product information call toll-free 1-800-688-7734. For other worldwide sales office telephone numbers and a full address list, please go to:

<http://www.hexcel.com/contact/salesoffice>

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